

3875081 G E SOLID STATE
Triacs

01E 17747 D F-25-17

2N5441-2N5446, T6420 Series

File Number 593

40-A Silicon Triacs

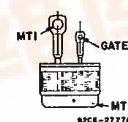
Features:

- di/dt capability = 100 A/ μ s
- Low switching losses
- Low on-state voltage at high current levels
- Low thermal resistance

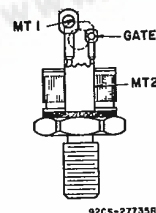
Package \ Voltage	200 V Types	400 V Types	600 V Types
Press-Fit	2N5441	2N5442	2N5443
Stud	2N5444	2N5445	2N5446
Isolated-Stud	T6420B	T6420D	T6420M

RCA triacs are gate-controlled, full-wave silicon ac switches. They are designed to switch from an off-state to an on-state for either polarity of applied voltage with positive or negative gate-triggering voltages.

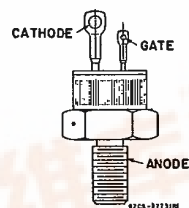
TERMINAL DESIGNATIONS



2N5441-43



T6420 Series



2N5444-46

MAXIMUM RATINGS, Absolute-Maximum Values:

For Operation with Sinusoidal Supply Voltage at Frequencies up to 50/60 Hz and with resistive or Inductive Load

	2N5441 2N5444 T6420B	2N5442 2N5445 T6420D	2N5443 2N5446 T6420M	
* REPETITIVE PEAK OFF-STATE VOLTAGE $\bullet$, V_{DROM} Gate Open, $T_J = -65$ to 100°C	200	400	600	V
RMS ON-STATE CURRENT (Conduction angle = 360°), $I_{T(RMS)}$ Case temperature				
• $T_C = 70^\circ\text{C}$ (Press-fit types)	40	40	40	A
• $T_C = 65^\circ\text{C}$ (Stud types)	40	40	40	A
• $T_C = 60^\circ\text{C}$ (Isolated-stud types)	40	40	40	A
For other conditions	See Fig. 3			
PEAK SURGE (NON-REPETITIVE) ON-STATE CURRENT, I_{TSM} For one cycle of applied principal voltage	300	265	265	A
• 60 Hz (sinusoidal)	300	265	265	A
• 50 Hz (sinusoidal)	265	265	265	A
For more than one cycle of applied principal voltage	See Fig. 4			
RATE OF CHANGE OF ON-STATE CURRENT, di/dt $V_{DM} = V_{DROM}$, $I_{GT} = 200$ mA, $t_i = 0.1$ μ s (See Fig. 12)	100	100	100	A/ μ s
FUSING CURRENT (for Triac Protection), I^2t $T_J = -65$ to 110°C , $t = 1.25$ to 10 ms	450	450	450	A ² s
* PEAK GATE-TRIGGER CURRENT $\blacksquare$, I_{GTM} For 1 μ s max.	12	12	12	A
* GATE POWER DISSIPATION Peak (For 10 μ s max., $I_{GTM} \leq 4$ A, P_{GM}	40	40	40	W
Average, $P_{G(AVG)}$	0.75	0.75	0.75	W
* TEMPERATURE RANGE Δ Storage, T_{stg}	-65 to 150	-65 to 150	-65 to 150	$^\circ\text{C}$
Operating (Case), T_C	-65 to 110	-65 to 110	-65 to 110	$^\circ\text{C}$
* TERMINAL TEMPERATURE (During Soldering), T_T For 10 s max. (terminals and case)	225	225	225	$^\circ\text{C}$
STUD TORQUE, τ_s Recommended	35	35	35	In-lb
Maximum (DO NOT EXCEED)	50	50	50	In-lb

* In accordance with JEDEC registration data format (JS-14, RDF2) filed for the JEDEC (2N-Series) types.

• For either polarity of main terminal 2 voltage (V_{MT2}) with reference to main terminal 1.■ For either polarity of gate voltage (V_G) with reference to main terminal 1. Δ For temperature measurement reference point, see Dimensional Outline

2N5441-2N5446, T6420 Series

ELECTRICAL CHARACTERISTICS

At Maximum Ratings Unless Otherwise Specified and at Indicated Case Temperature (T_C)

CHARACTERISTIC	SYMBOL	LIMITS			UNITS		
		FOR ALL TYPES UNLESS OTHERWISE SPECIFIED					
		MIN.	TYP.	MAX.			
Peak Off-State Current: [⚡] Gate open, $T_J = 110^\circ\text{C}$, $V_{DROM} = \text{Max. rated value}$	I_{DROM}	—	0.2	4*	mA		
Maximum On-State Voltage: [⚡] For $I_T = 100\text{ A (peak)}$, $T_C = 25^\circ\text{C}$ For $I_T = 56\text{ A (peak)}$, $T_C = 25^\circ\text{C}$	V_{TM}	— —	1.7 1.5	2 1.85*	V		
DC Holding Current: [⚡] Gate open, Initial principal current = 500 mA (dc), $v_D = 12\text{V}$: $T_C = 25^\circ\text{C}$ $T_C = -65^\circ\text{C}$ For other case temperatures	I_{HO}	— —	25 —	60 100*	mA		
See Fig. 6							
Critical Rate of Rise of Commutation Voltage: [⚡] For $v_D = V_{DROM}$, $I_T(\text{RMS}) = 40\text{ A}$, commutating $di/dt = 22\text{ A/ms}$, gate unenergized, (See Fig. 13): $T_C = 70^\circ\text{C}$ (Press-fit types) $T_C = 65^\circ\text{C}$ (Stud types) $T_C = 60^\circ\text{C}$ (Isolated-stud types)	dv/dt	5* 5* 5	30 30 30	— — —	V/ μs		
Critical Rate of Rise of Off-State Voltage: [⚡] For $v_D = V_{DROM}$, exponential voltage rise, gate open, $T_C = 110^\circ\text{C}$: 2N5441, 2N5444, T6420B. 2N5442, 2N5445, T6420D. 2N5443, 2N5446, T6420M.	dv/dt	50* 30* 20*	200 150 100	— — —	V/ μs		
DC Gate-Trigger Current: ^{⚡⚡} For $v_D = 12\text{ V (dc)}$, $R_L = 30\ \Omega$, $T_C = 25^\circ\text{C}$	Mode I^+ positive III^- negative I^- positive III^+ negative	V_{MT2} positive negative positive negative	V_G positive negative negative positive	— — — —	15 20 30 40	50 50 80 80	mA
For $v_D = 12\text{ V (dc)}$, $R_L = 30\ \Omega$, $T_C = -65^\circ\text{C}$	Mode I^+ positive III^- negative I^- positive III^+ negative	V_{MT2} positive negative positive negative	V_G positive negative negative positive	— — — —	— — — —	125* 125* 240* 240*	mA
For other case temperatures See Figs. 7 & 8							
DC Gate-Trigger Voltage: ^{⚡⚡} For $v_D = 12\text{ V (dc)}$, $R_L = 30\ \Omega$, $T_C = 25^\circ\text{C}$ $T_C = -65^\circ\text{C}$ For other case temperatures For $v_D = V_{DROM}$, $R_L = 125\ \Omega$, $T_C = 110^\circ\text{C}$	V_{GT}	— — 0.2	1.35 1.8 —	2.5 3.4* —	V		
See Fig. 9							
Gate-Controlled Turn-On Time: (Delay Time + Rise Time) For $v_D = V_{DROM}$, $I_{GT} = 200\text{ mA}$, $t_r = 0.1\ \mu\text{s}$, $I_T = 60\text{ A (peak)}$, $T_C = 25^\circ\text{C}$ (See Figs. 10 & 14)	t_{gt}	—	1.7	3	μs		
Thermal Resistance, Junction-to-Case: Steady-State Press-fit types Stud types Isolated-stud types Transient (Press-fit & stud types)	$R_{\theta JC}$	— — — —	— — — —	0.8* 0.9* 1	$^\circ\text{C/W}$		
See Fig. 11							

* In accordance with JEDEC registration data format (JS-14, RDF 2) filed for the JEDEC (2N-Series) types.

⚡ For either polarity of main terminal 2 voltage (V_{MT2}) with reference to main terminal 1.⚡⚡ For either polarity of gate voltage (V_G) with reference to main terminal 1.

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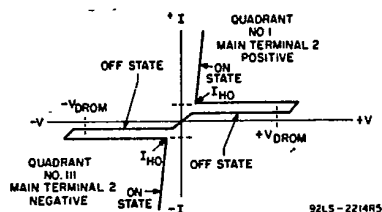


Fig. 1 - Principal voltage-current characteristic.

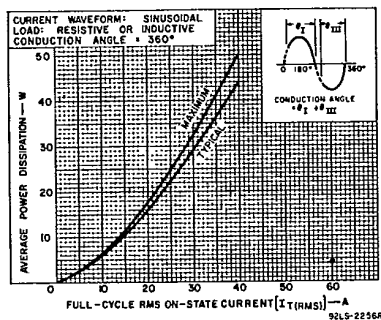


Fig. 2 - Power dissipation vs. on-state current.

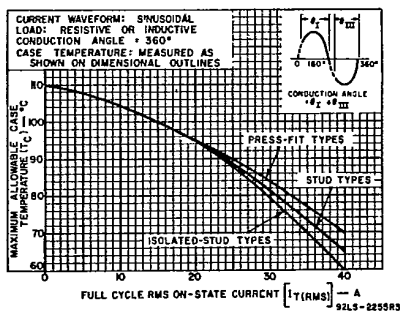


Fig. 3 - Maximum allowable case temperature vs. on-state current.

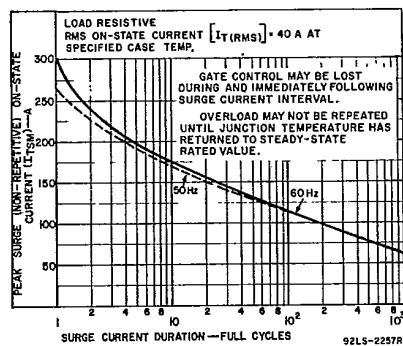


Fig. 4 - Peak surge on-state current vs. surge current duration.

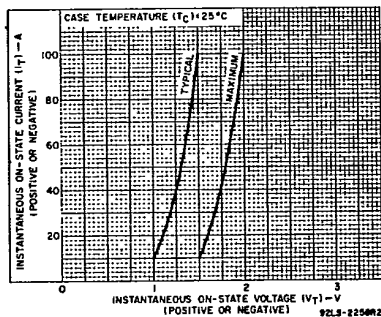


Fig. 5 - On-state current vs. on-state voltage.

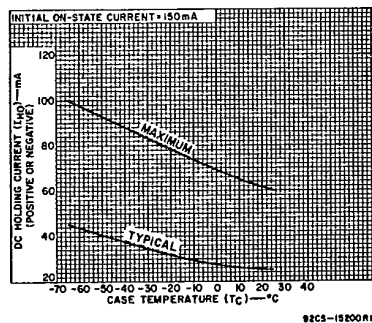


Fig. 6 - DC holding current vs. case temperature.

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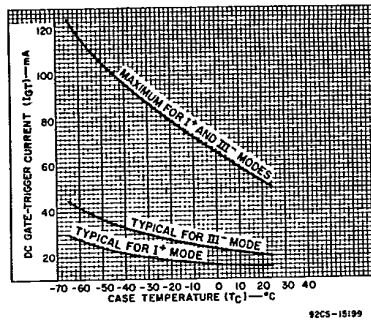
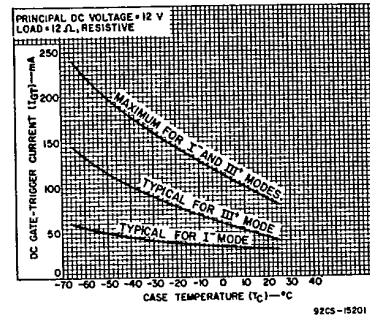
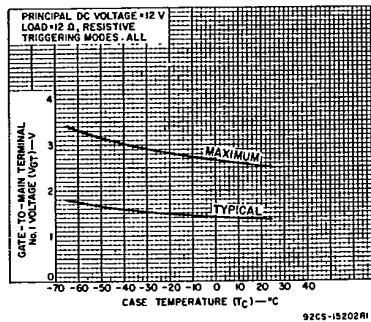
Fig. 7 - DC gate-trigger current vs. case temperature (I^+ & III^+ modes).Fig. 8 - DC gate-trigger current vs. case temperature (I^- & III^- modes).

Fig. 9 - DC gate trigger voltage vs. case temperature.

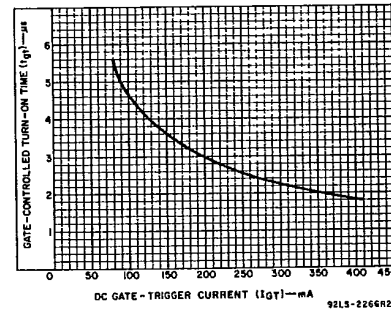


Fig. 10 - Turn-on time vs. gate-trigger current.

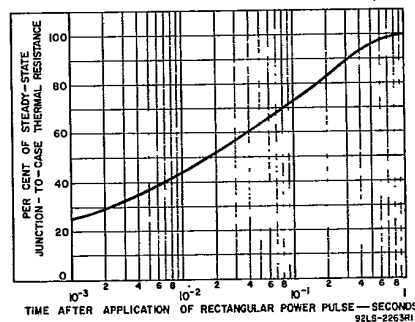
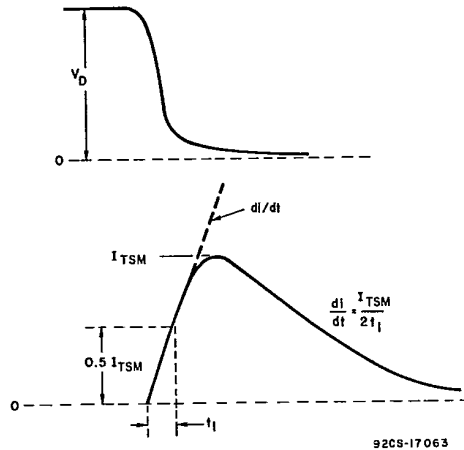
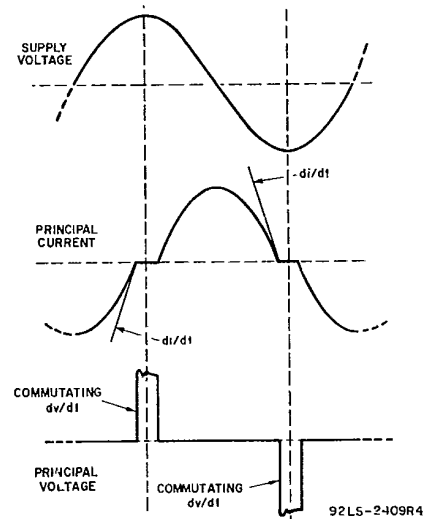
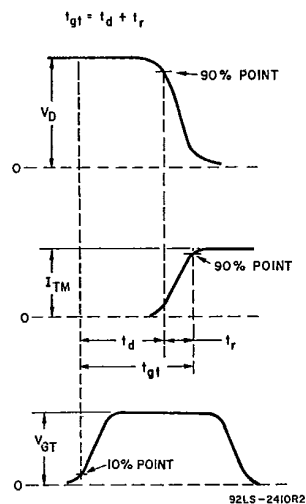


Fig. 11 - Transient junction-to-case thermal resistance vs. time for press-fit and stud types.

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Fig. 12 - Rate of change of on-state current with time (defining di/dt).Fig. 13 - Relationship between supply voltage and principal current (inductive load) showing reference points for definition of commutating voltage (dv/dt).Fig. 14 - Relationship between off-state voltage, on-state current, and gate-trigger voltage showing reference points for definition of turn-on time (t_{gt}).